



FAST & FLEXIBLE MOUNTER DECAN S1

Next generation medium speed chip mounter Decan S1.

- Improves actual productivity
- Improves placement quality
- Reduces loss rates

As a chip mounter which was developed focusing on visible improvements. one of the three major indexes, this chip mounter provides the optimum productivity necessary for batch production.

Specifications

Model Name		Decan S1
Alignment		Fly Camera + Fix Camera
The number of Spindles		10 spindles x 1 Gantry
Placement Speed		47,000 CPH (Optimum)
Placement Accuracy	Chip QFP	±28 μm @ Cpk ≥ 1.0 ±30 μm @ Cpk ≥ 1.0
Component Range	Fly Camera Fix Camera Max. Height	~42mm (Standard) 42mm~55mm (MFOV) L55mm~L75mm Connector (MFOV) 10mm (Fly), 15mm (Fix)
PCB Size (mm)	Min. Max. Standard Option	L50x W40* L50x W40 ~Max. L1,500 x W460, L1,500 x W510
PCB Thickness (mm)		0.38~4.2
Feeder Capacity (8mm standard)	Standard Option	60ea / 56ea (Fixed feederbase / Docking Cart) 120ea / 112ea (Fixed feederbase / Docking Cart)

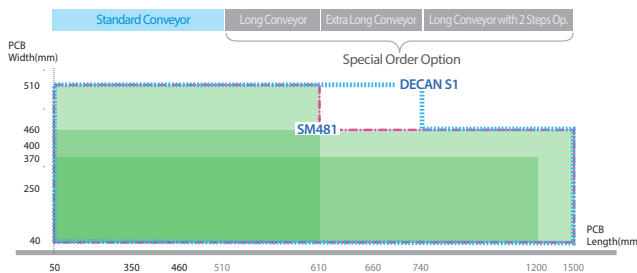
Model Name		Decan S1
Utility	Power	3Phase AC200 / 208 / 220 / 240 / 380 / 415V Max. 3.5kVA
	Air Consumption	5.0~7.0kgf/cm2 50Nℓ/min (Vacuum Pump)
Weight (H900 mm standard)		Approx.1,600 kg
Externa Dimension (Standard)		1,430(L) x 1,740(D) x 1,485(H) mm

If the PCB lenght is 1,500mm, the minimun size oh the PCB should be 150x90mm

Highest performance among chip mounters of the same class

Highest applicability of medium speed chip mounters to PCBs

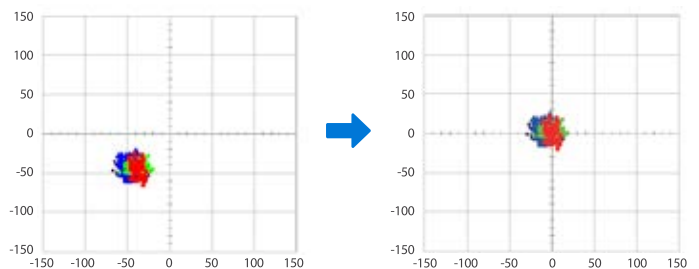
- 510 x 510mm (standard) / 1500 x 460mm (option)
- Possible to produce PCBs up to 1,500mm(L) x 460mm(W) in size



Places microchips stably

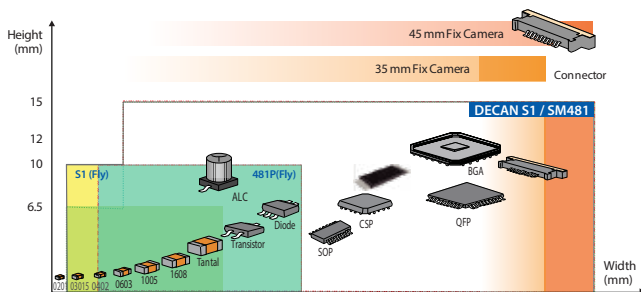
Run time calibration

- Maintains placement accuracy by performing automatic calibration during production



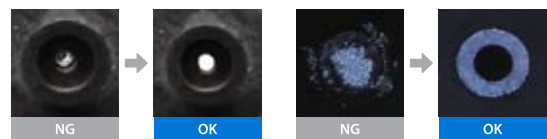
Expands the component recognition range with a high pixel camera

- The fly camera can recognize all chips of 03015 ~ 16mm



Maintains pickup and placement quality by using a nozzle maintenance unit

- Measurement: Measures vacuum flow rate as well as spring tension
- Cleaning with high pressure air blow: Removes foreign materials on a nozzle
- Remeasurement: Determines whether to start operation again and replaces a defective nozzle



Enables early production of new products and initial products

- In the event of component recognition failure during initial product production, components are placed by editing / applying the component information and PCB coordinate without dumping them
- Waste of components (zero) / Rapid model change / Allows mass-production from the initial product

Semi-extend mode

- For Array PCB production, allows easy teaching by managing the placement coordinates in the Non-Extend Mode while maintaining high productivity in the Extend Mode

Improves simultaneous pickup rate

- Arranges pocket positions automatically through communication between the machine and feeder

Improves the placement speed of an odd-shape component

- Increases speed by approximately 25% by optimizing the fix camera recognized motion sequence

Increased convenience of operation

Reduces the teaching time of a large odd-shape component

- Expanded FOV of Fiducial Camera: □ 7.5mm → □ 12mm
 - Reduces the time to teach the component pickup / placement point and improves the convenience of teaching

Maintains the pickup coordinate of the common feeder

- When changing a model, reduces the model changing time by succeeding the pickup information of a similar model

Unifies the chip component lighting level

- By setting the same lighting value collectively, minimizes the lighting changing time, removes the productivity deviation by machine and improves the convenience of part DB management

Support of multi-vendor component

- It's possible to manage the same components supplied by two suppliers in one part name, so it's Possible to perform production continuously without changing the PCB program for the components supplied by different vendors

Teaches large-sized components easily (Panoramic view)

- Performs split-recognition of a large-sized component that is out of the camera recognition range (FOV) and merges split component images into a single image before displaying.
 - Easily teaches the pickup / placement position of a large-sized component